

Amendments to the Specification

Please replace the paragraph beginning at page 3, line 3, with the following rewritten paragraph:

Then, metal foil ~~115b~~105b, pre-preg sheet 101b, double-sided circuit board 110, pre-preg sheet 101a, and metal foil ~~115a~~105a are heated and pressurized by hot press. Thus, as shown in Fig. 7C, pre-preg sheets 101a and 101b are compressed to have thickness t102, and are bonded to double-sided circuit board 110 and metal foil ~~115a~~105a and ~~115b~~105b. Circuit patterns 106a and 106b are electrically connected to metal foils 105a and 105b via conductive paste 104, respectively.

Please replace the paragraph beginning at page 3, line 10, with the following rewritten paragraph:

As shown in Fig. 7D, metal foils ~~115a~~105a and ~~115b~~105b is selectively etched to form circuit patterns 106a and 106b, thus providing four-layer circuit board 120.

Please replace the paragraph beginning at page 10, line 4, with the following rewritten paragraph:

As shown in Fig. 6F, laminated body 181 was then mounted on a vacuum hot pressing machine, heated, and pressurized. Fig. 3 shows temperature profile Tp1 and temperature Tb1 of the laminated body at this moment. A temperature-rising rate of the resin of laminated body 181 within flowing/hardening range ~~R1-R2~~ was determined to be 5°C/min., and laminated body 181 was pressurized at pressure of 5MPa in range R1 to be molded.